

RESIN COMPOSITION FOR ENCAPSULATION AND ELECTRONIC
COMPONENT DEVICE

ABSTRACT

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A resin composition for encapsulation according to the present invention includes: a phenol resin-based curing agent (A) essentially containing a polymer component (A-1) in which a biphenylene group-containing structural unit
10 bonds a monovalent hydroxyphenylene structural unit and a polyvalent hydroxyphenylene structural unit together and a polymer component (A-2) in which the biphenylene group-containing structural unit bonds the polyvalent hydroxyphenylene structural units together; an epoxy resin
15 (B); and an inorganic filler (C). This makes it possible to economically obtain a resin composition for encapsulation having soldering resistance, flame resistance, continuous moldability, flowability and high temperature storage stability in an excellent balanced manner, and an
20 electronic component device produced by encapsulating an element with a cured product thereof and having high reliability.

FIG. 2 accompanies the abstract